/ Descriptions

1.0A ABF
1.0A Surface Mount Glass Passivated Bridge Rectifier, ABF thin package.

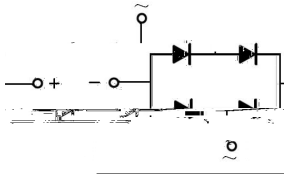
/ Features

1000V 1.0A
Glass Passivated Chip Junction,Reverse Voltage: 1000V,Forward Current:1.0A, Fast reverse recovery time,Designed for Surface Mount Application.Halogen free product.

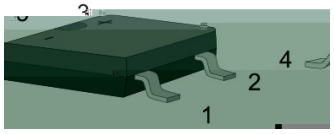
/ Applications

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General purpose.

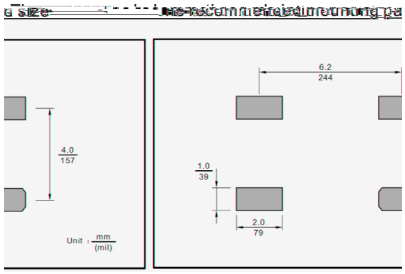
/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
3	Output Anode



/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at T_c = 125	I_o	1.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30	A
Typical Junction Capacitance Note1	C_j	30	pF
Typical Thermal Resistance Note2	$R_{\theta JA}$	75	/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~150	

Note:

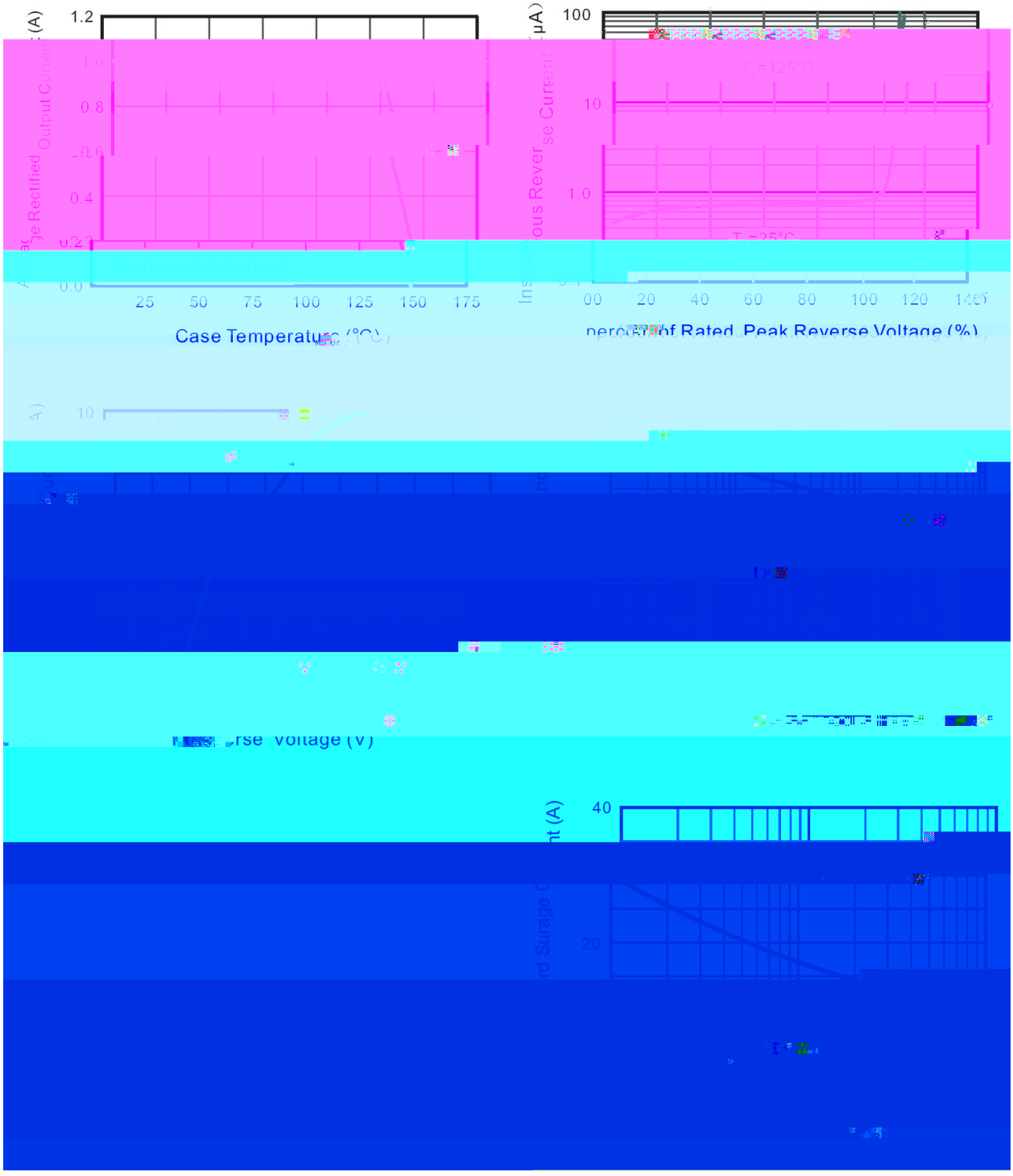
1.Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4 1.0" X 1.0" (2.54 X 2.54 cm) copper pad.

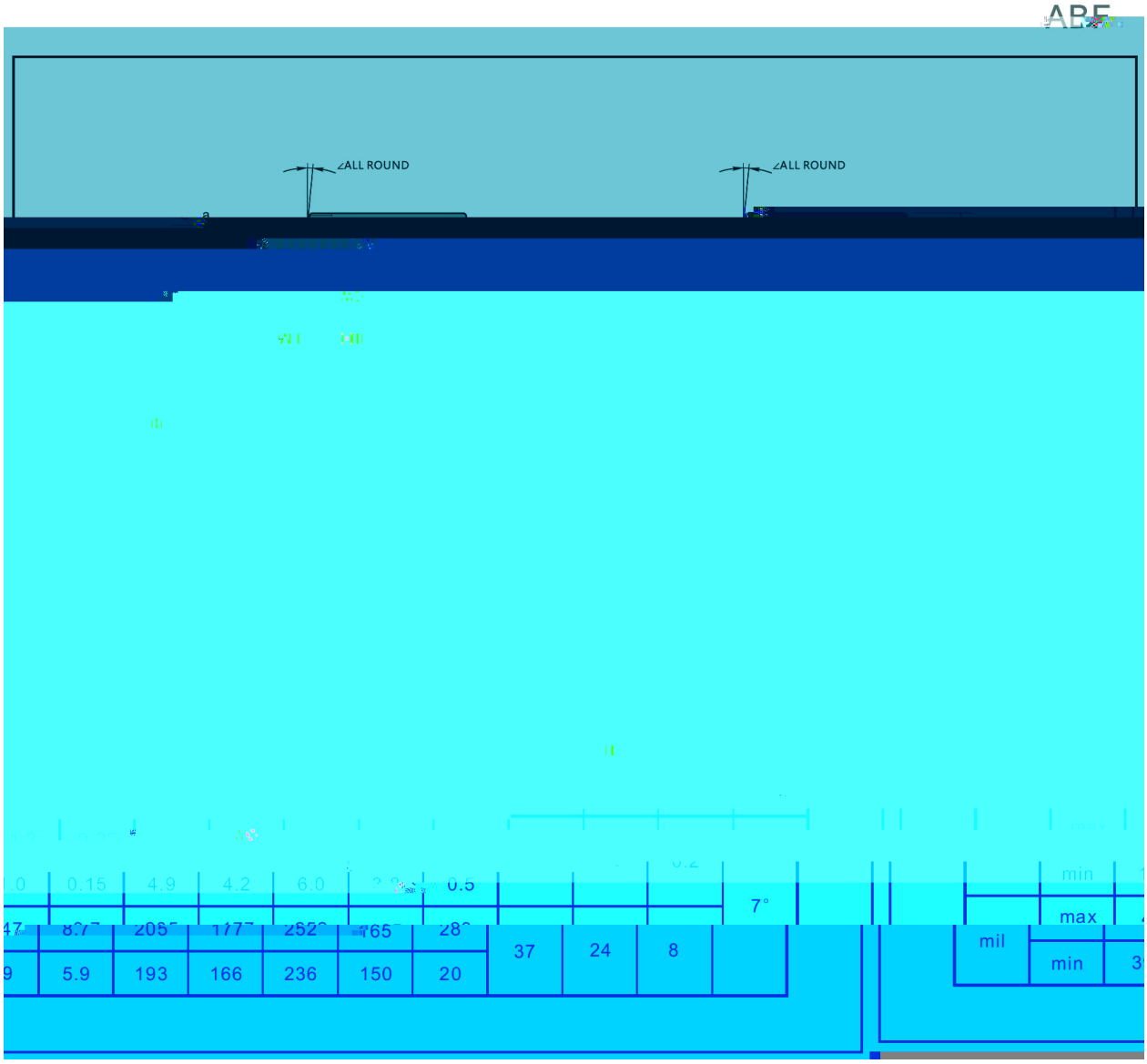
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	I_F=1.0A	1.3	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25	5.0	μA
		T_a=125	50	μA
Maximum Reverse Recovery Time	t_{rr}	I_F =0.5A I_R=1.0A I_{rr}=0.25A	200	ns

/ Electrical Characteristic Curve

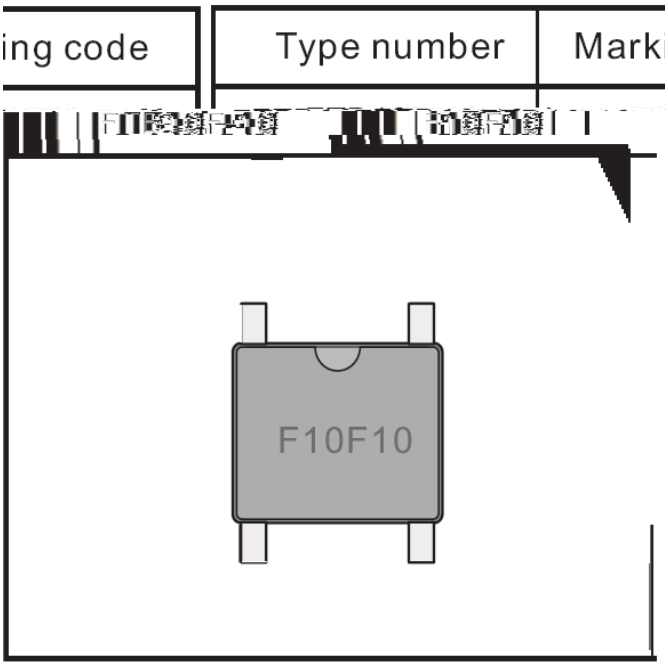


/ Package Dimensions



/ Marking Instructions

Marking

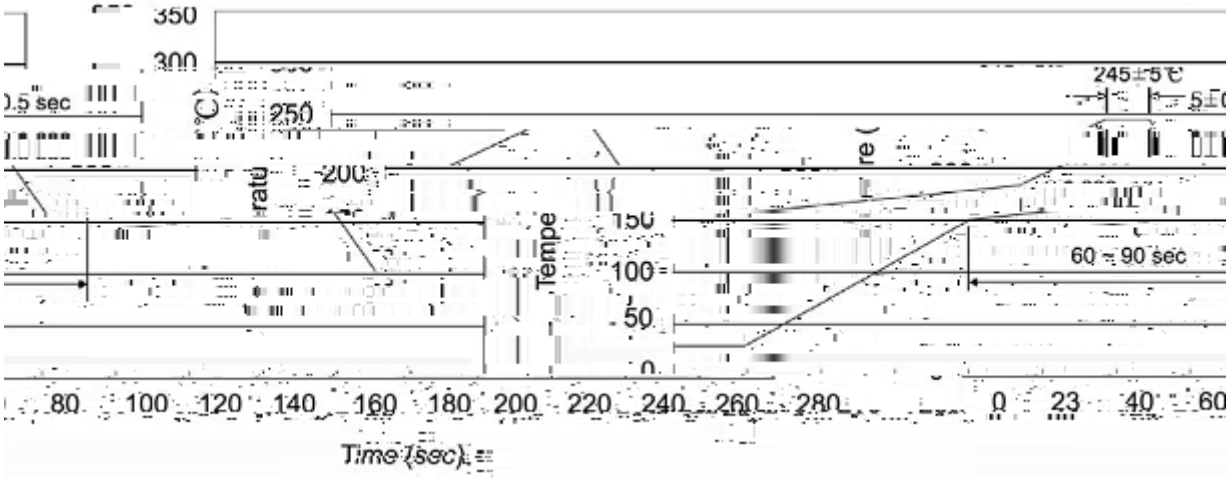


/ Marking Instructions

F10F10
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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



				Note:	
1	25	150	60 90sec;	1.Preheating:25~150	, Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5	, Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10	/sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm^3)
	5000	2	10000	5	50000	13 ×15	336X336X40	380X335X366

/ Notices